

## AMENDMENTS TO THE CLAIMS

1. **(Currently Amended)** A circuit board including chip components mounted thereon, the circuit board comprising:

a substrate including electrode patterns formed thereon;

plural first chip components having a first side and a second side opposite the first side,  
the first side mounted through conductive bonding material on said substrate, which are said  
plural first chip components included in said chip components and including a first chip  
component and a second chip component and mounted through a conductive bonding material  
on said substrate; and

a second third chip component having a first electrode and a second electrode, and which  
is included in said chip components, and said third chip component being mounted through a  
conductive bonding material on a said second side of said plural first chip components opposite  
from said substrate;

wherein one said first chip component and the other first said second chip component-  
included in said plural first chip components have substantially a same height on said substrate,  
and said second third chip component is bonded at one said first electrode to an electrode of  
said one first chip component and is bonded at the other said second electrode to an electrode of  
said other first second chip component such that said third chip component is arranged  
orthogonally to said first chip component and said second chip component.

2. **(Currently Amended)** The circuit board according to Claim 1, wherein each of  
said plural first chip components and said second third chip component have lengths of 2 mm or  
less.

3. **(Currently Amended)** The circuit board according to Claim 1, wherein each of  
said plural first chip components and said second third chip component are resistors, condensers  
or inductors.

4. **(Currently Amended)** The circuit board according to Claim 1, further comprising

a reinforcing resin configured to cover junctions between said plural first chip components and said second-third chip component on said substrate.

**5. (Currently Amended)** A circuit board including chip components mounted thereon, the circuit board comprising:

a substrate including electrode patterns formed thereon;

~~a first chip component~~ components which ~~is~~ are included in said chip components and mounted through a conductive bonding material on said substrate, said first chip components including a first chip component; and

a second chip component which is included in said chip components and mounted through a conductive bonding material on a side of said first chip components opposite from said substrate;

wherein ~~as~~ said first chip component included in said first chip components is a component of a different type from the second chip component, and said second chip component is bonded to an electrode of said first chip component such that said second chip component is arranged orthogonally to said first chip component.

**6-18. (Cancelled)**